

**IN THE CLAIMS**

Please amend the claims as follows:

Claim 1 (currently amended): A multilayer printed circuit board ~~including~~  
comprising:

a substrate having an inner-layer conductor circuit formed inside the substrate and ~~one~~  
~~or more~~ an outer-layer conductor ~~circuit~~ circuit formed on the substrate; ~~with an insulating~~  
~~layer laid between the substrate and outer layer conductor circuit, wherein:~~

a strain gauge ~~having~~ formed inside the substrate and comprising a plurality of resin  
films and a resistive element held ~~tight~~ between the resin films, each of the resin films  
comprising one of ~~formed from~~ polyimide ~~[[or]]~~ and a thermoplastic resin ~~is buried in the~~  
~~substrate; and~~

a plurality of electrodes electrically connected to the resistive element ~~[[are]]~~ and  
~~exposed to outside from one of the resin [[film]] films; and~~

a plurality of viaholes ~~[[are]]~~ electrically connected ~~at exposed portions thereof to a~~  
~~viahole to the electrodes, respectively, through the one of the resin films.~~

Claim 2 (currently amended): The multilayer printed circuit board according to claim  
1, wherein each of the resin films ~~are formed from at least~~ comprises one selected from the  
group consisting of polyimide, ~~or thermoplastic resins such as polyester, and~~  
~~polytetrafluoroethylene, etc.~~

Claim 3 (original): The multilayer printed circuit board according to claim 1 or 2,  
wherein the viahole is filled with a conductive material.

Claim 4 (currently amended): The multilayer printed circuit board according to ~~any~~  
~~one of claims 1 to 3, having~~ claim 1, further comprising an outermost layer formed on the  
substrate and a plurality of solder bumps or balls formed on the outermost layer ~~thereof~~.

Claim 5 (currently amended): A testing piece for ~~[[the]]~~ a printed circuit board including comprising:

a substrate having an inner-layer conductor circuit formed inside the substrate and ~~one or more~~ an outer-layer conductor ~~circuits~~ circuit formed on the substrate; ~~with an insulating layer laid between the substrate and outer layer conductor circuit, wherein:~~

a strain gauge ~~having~~ formed inside the substrate and comprising a plurality of resin films and a resistive element held ~~tight~~ between the resin films, each of the resin films comprising one of ~~formed from~~ polyimide ~~[[or]]~~ and a thermoplastic resin ~~is buried in the substrate; [[and]]~~

a plurality of electrodes electrically connected to the resistive element ~~[[are]]~~ and exposed ~~to outside~~ from one of the resin ~~[[film]]~~ films; and

a plurality of viaholes ~~[[are]]~~ electrically connected ~~at exposed portions thereof to a viahole~~ to the electrodes, respectively, through the one of the resin films.

Claim 6 (currently amended): The testing piece for the printed circuit board according to claim 5, wherein each of the resin films ~~are formed from at least~~ comprises one selected from polyimide, ~~or thermoplastic resins such as polyester, and~~ polytetrafluoroethylene, ~~etc.~~

Claim 7 (original): The ~~printed circuit board~~ testing piece according to claim 5 or 6, wherein the viahole is filled with a conductive material.

Claim 8 (currently amended): The ~~multilayer printed circuit board~~ testing piece according to ~~any one of claims 5 to 7, having claim 1, further comprising an outermost layer~~ formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer ~~thereof.~~

Claim 9 (new): The multilayer printed circuit board according to claim 2, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 10 (new): The multilayer printed circuit board according to claim 3, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 11 (new): The multilayer printed circuit board according to claim 1, wherein the resistive element of the strain gauge comprises a metallic foil having a lattice shape.

Claim 12 (new): The multilayer printed circuit board according to claim 1, wherein the resistive element of the strain gauge has a plurality of portions formed as the plurality of electrodes.

Claim 13 (new): The multilayer printed circuit board according to claim 1, wherein the substrate comprises a plurality of insulating layers, and the inner-layer conductor circuit and the strain gauge are provided between the insulating layers.

Claim 14 (new): The multilayer printed circuit board according to claim 1, wherein the resistive element is laminated between the resin films by hot-press such that the resistive element is held tight between the resin films.

Claim 15 (new): The test piece according to claim 6, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 16 (new): The test piece according to claim 7, further comprising an outermost layer formed on the substrate and a plurality of solder bumps or balls formed on the outermost layer.

Claim 17 (new): The multilayer printed circuit board according to claim 5, wherein the resistive element of the strain gauge comprises a metallic foil having a lattice shape.

Claim 18 (new): The multilayer printed circuit board according to claim 5, wherein the resistive element of the strain gauge has a plurality of portions formed as the plurality of electrodes.

Claim 19 (new): The multilayer printed circuit board according to claim 5, wherein the substrate comprises a plurality of insulating layers, and the inner-layer conductor circuit and the strain gauge are provided between the insulating layers.

Claim 20 (new): The multilayer printed circuit board according to claim 5, wherein the resistive element is laminated between the resin films by hot-press such that the resistive element is held tight between the resin films.